

Investor
Relations
2024

 GAONCHIPS

Your Partner in Semiconductor Innovation

 GAONCHIPS


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AUG 2024
Investor Relations

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The Most Trusted Design Solution Partner

Empowering Your Success, All-round Best Track Record

SAMSUNG Foundry
Project Tape-outs

Over **220**



Technology
Experiences

Up to **2nm**



Revenue from
AI/HPC & Automotive

Over **70%**



Number of
Employees

Over **260**



2020 to 2024
CAGR

Over **50%**

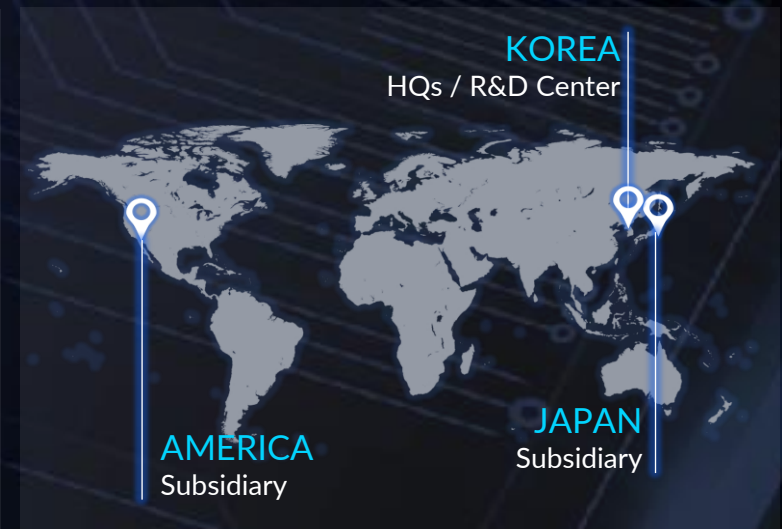
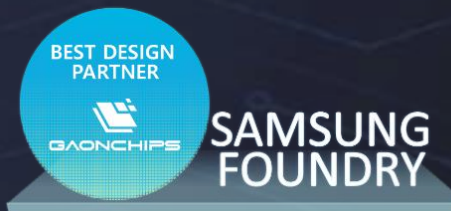
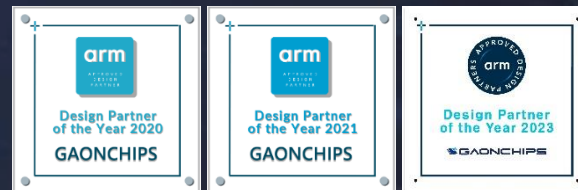


Revenue from
≤14nm Advance node

Over **80%**



- 2024 Arm Design Partner of the Year 2023
SYNOPTIS IP OEM Partner
- 2022 Arm Design Partner of the Year 2021
IPO (Listed on the KOSDAQ)
- 2021 Arm Design Partner of the Year 2020
- 2020 AADP (Arm Approved Design Partner)
- 2019 SAMSUNG FOUNDRY Best Design Partner
SAMSUNG FOUNDRY Design Solution Partner
- 2018 SAMSUNG FOUNDRY MPW Partner
- 2017 SAMSUNG FOUNDRY Channel Partner
- 2014 SAMSUNG Electronics ASIC Design Service Partner
- 2012 GAONCHIPS Co., Ltd. Founded



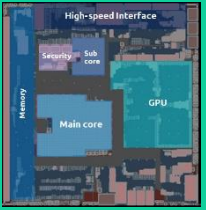
Design solution company supports design and entire process of before and after production

“ The design solution company has emerged as a 'hub' leading the joint growth of Fabless, Foundry, and OSAT ”



	IP Vendors	Fabless	Foundry	OSAT	End Customer
Future Producer (Chipless)		Supporting mass production of ASIC semiconductor for End customers Supply ASIC semiconductors by providing 'A to Z services' related to semiconductor design and mass production to end-customers such as OEMs, Set makers, and Big tech who want their chip independence			
Now Facilitator (Turn-key)		Provides turnkey service for fabless Support more difficult designs such as pre-design and collaborate with IP vendor and OSAT companies to conduct turnkey business			
Before Broker		Fabless Design Service Process design support, Foundry customer responsiveness			

Tailor-made Full Turnkey Solution From Design Planning to Mass Production

FULL CHIP DESIGN	xPU HARDENING	PHYSICAL IMPLEMENTATION	PHYSICAL DESIGN	PKG & TEST DEVELOP	PRODUCT MANUFACTURING
 <ul style="list-style-type: none"> • Design / Verification Platform • System Architecture Design • Functional Safety • FPGA Prototyping • Device Driver, BSP, OS porting 	 <ul style="list-style-type: none"> • IP Supplier Partnership • PPA Optimization (Power/Area/Performance) • Floorplan & Layout (Hard Macro IP, SRAM) 	 <ul style="list-style-type: none"> • DFT (SCAN/BIST/JTAG) • In-system Test • STA (Static Timing Analysis) • Synthesis & Timing Closure 	 <ul style="list-style-type: none"> • Full Chip Floor Plan • Hierarchical Physical Layout • Low Power Design • SI Check (IR Drop, Crosstalk-Noise) 	 <ul style="list-style-type: none"> • Package Design Guide • Off-chip PSI Simulation • Test vector generation • ATE test set-up • Qualification & Reliability 	 <ul style="list-style-type: none"> • Wafer Business • Full Turn-key Business (Wafer + PKG + TEST) • QA & Failure analysis

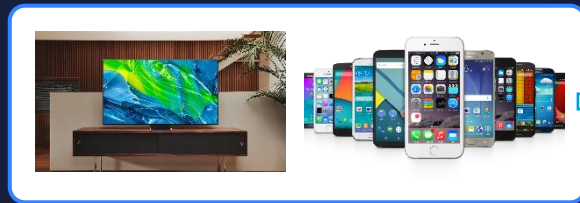


	SoC Design	Synthesis	Netlist Hand-off	DFT Service	Placement & Routing	Physical Verification	Test /PKG	SCM (MP)
Level 0	✓	✓	✓	✓	✓	✓	✓	✓
Level 1		✓	✓	✓	✓	✓	✓	✓
Level 2			✓	✓	✓	✓	✓	✓
Level 3						✓	✓	✓

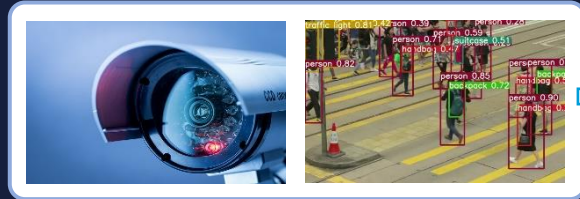
High-growth market oriented project portfolio

Automotive Heritage with various design experiences and competitiveness
(Robust Design, Advanced DFT (Inc. In-system Test), Etc.)
Ramp up the AI-powered HPC market

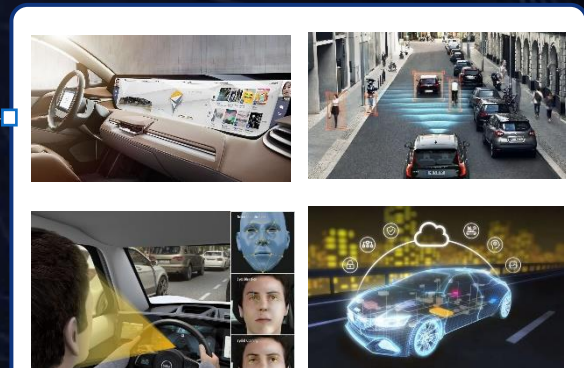
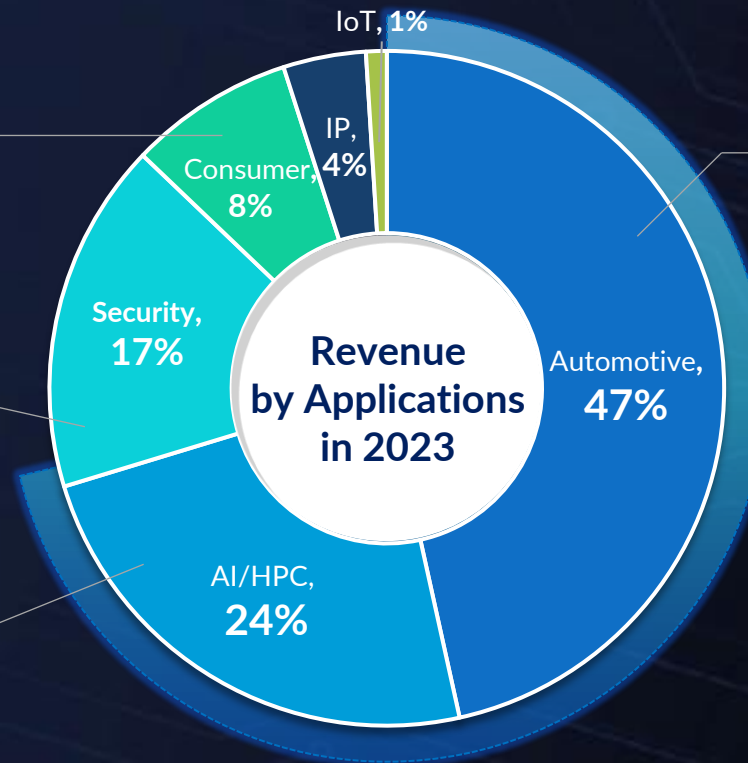
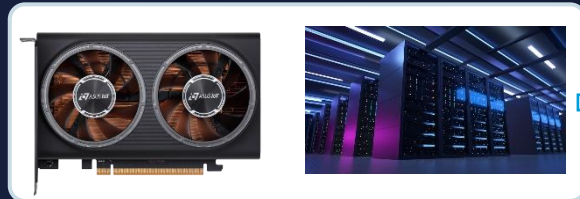
Display / Mobile / Entertainment



Surveillance



AI Accelerator / Server

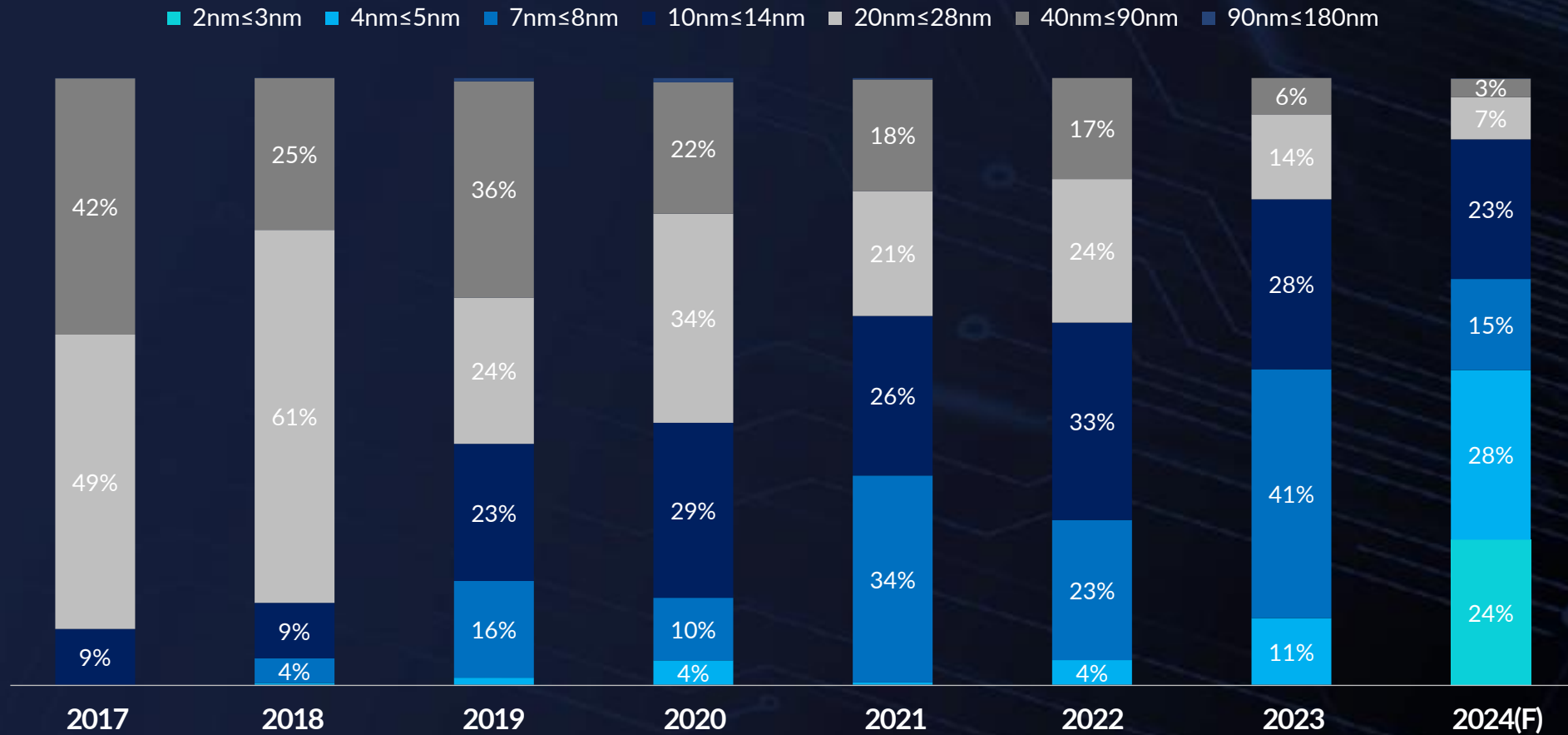


- Cluster/Infotainment System
- Rear/Surround-View / In-Cabin
- Network/Gateway Processor
- Vision Processor / ADAS

Focused on the Advanced Technology Node

Revenue Breakdown by Technology

(Unit: %)





US Subsidiary
San Jose



KOREA R&D Center
Pangyo

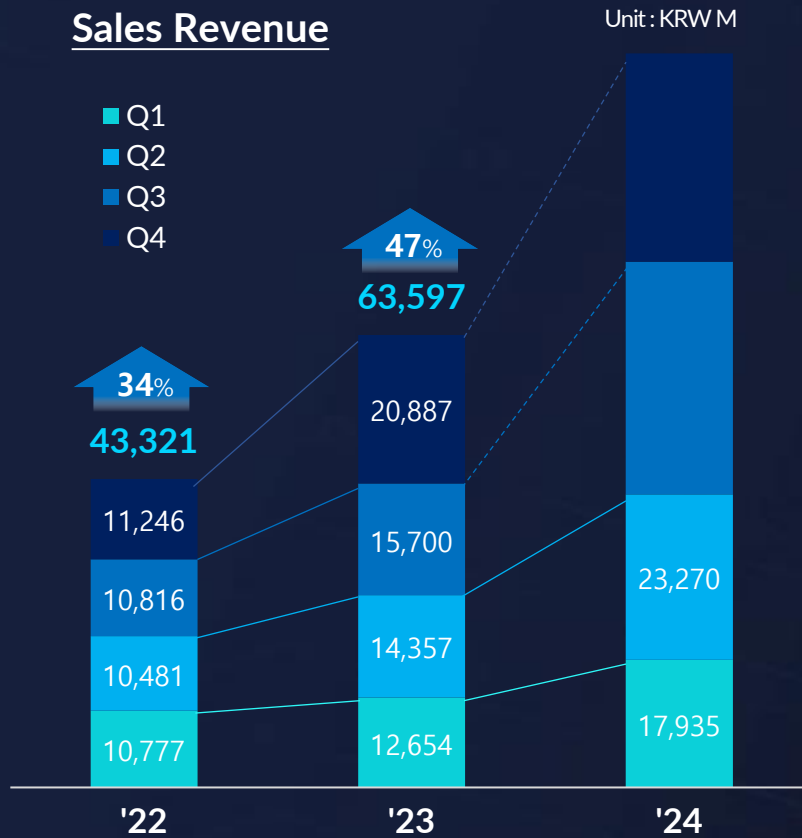


KOREA HQ
Pangyo



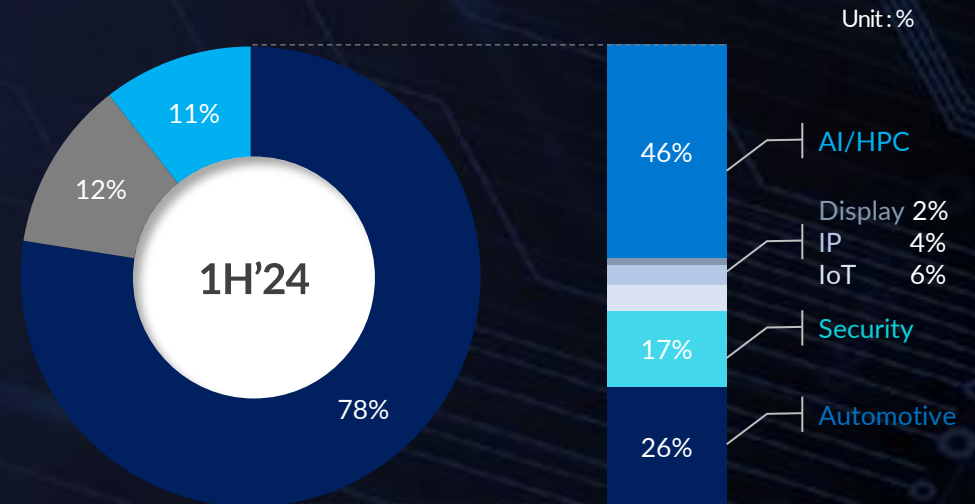
JAPAN Subsidiary
Tokyo

Sales Revenue



Sales Portfolio

- Turnkey NRE
- Outsourcing
- Mass Production



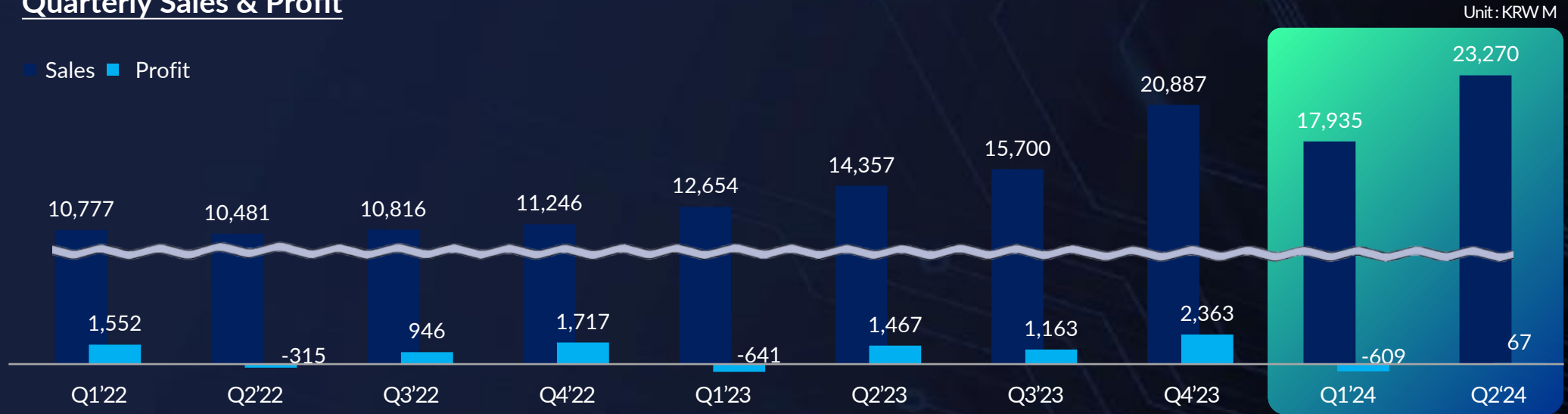
2024



- 1st Overseas Customer Project Win (JPN)
- Arm Best Design Partner of the Year
- US Office Launching (@San Jose)

- 2nm AI Project Design-Win
- SYNOPTIS IP OEM Partnership
- 5nm AI Project Launching for Mass Production

Quarterly Sales & Profit



Unit: KRW M

(연결기준)	2022년 (제11기)				2023년 (제12기)				2024년 (제13기)	
	1분기	2분기	3분기	4분기	1분기	2분기	3분기	4분기	1분기	2분기
매출액	10,777	10,481	10,816	11,246	12,654	14,357	15,700	20,887	17,935	23,270
매출원가	7,802	8,608	7,434	7,848	11,290	11,362	12,078	16,149	16,030	19,912
매출총이익	2,975	1,873	3,383	3,398	1,364	2,995	3,622	4,737	1,905	3,358
판매비와관리비	1,424	2,188	2,436	1,680	2,005	1,528	2,459	2,375	2,514	3,291
영업이익(손실)	1,552	(315)	946	1,717	(641)	1,467	1,163	2,363	(609)	67
당기순이익(손실)	1,664	12	755	1,988	40	1,697	1,073	3,535	(402)	1,510

“Your first and last design partner”



GAONCHIPS

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